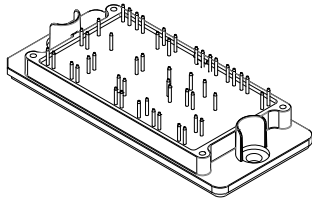


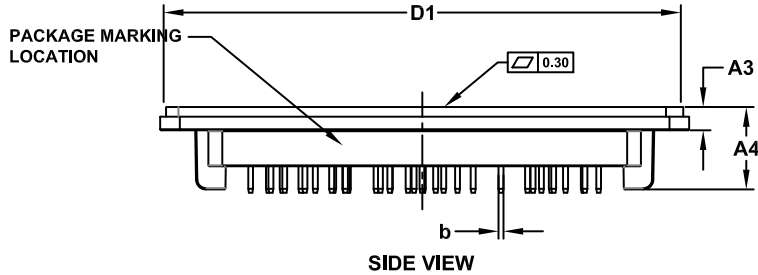
MECHANICAL CASE OUTLINE

PACKAGE DIMENSIONS



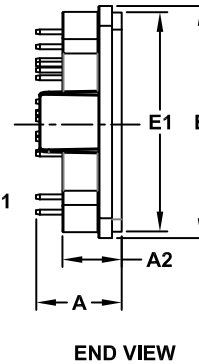
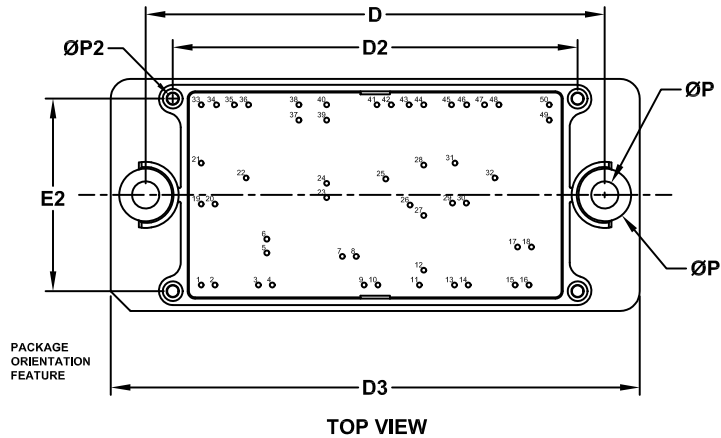
PIM56, 93x47 (SOLDER PIN)
CASE 180BK
ISSUE O

DATE 19 MAY 2022



NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 2009
2. CONTROLLING DIMENSION : MILLIMETERS
3. DIMENSIONS b AND b1 APPLY TO THE PLATED TERMINALS AND ARE MEASURED AT DIMENSION A1
4. PIN POSITION TOLERANCE IS $\pm 0.4\text{mm}$
5. PACKAGE MARKING IS LOCATED AS SHOWN ON THE SIDE OPPOSITE THE PACKAGE ORIENTATION FEATURES



DIM	MILLIMETERS		
	MIN.	NOM.	MAX.
A	16.80	17.20	17.60
A2	11.70	12.00	12.30
A3	4.40	4.70	5.00
A4	16.40	16.70	17.00
b	0.95	1.00	1.05
D	92.90	93.00	93.10
D1	104.45	104.75	105.05
D2	81.80	82.00	82.20
D3	106.90	107.20	107.50
E	46.70	47.00	47.30
E1	44.10	44.40	44.70
E2	38.80	39.00	39.20
P	5.40	5.50	5.60
P1	10.60	10.70	10.80
P2	1.80	2.00	2.20

NOTE 4

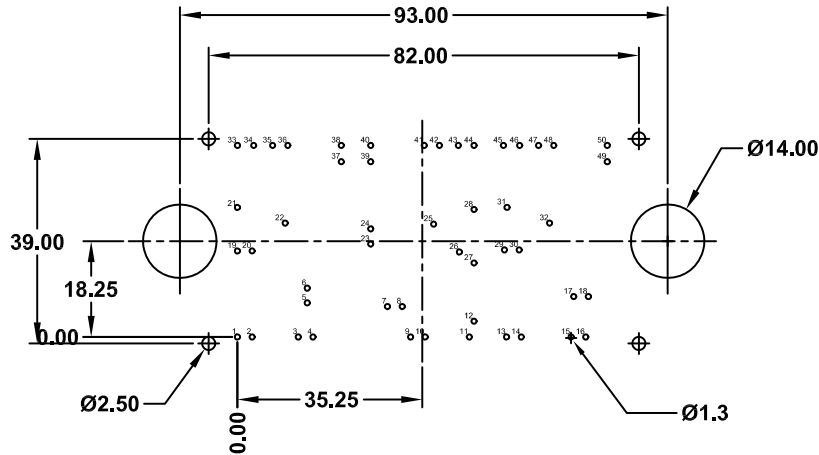
Pin #	X	Y	Function	Pin #	X	Y	Function
1	0	0	BSC12	26	42.3	16.2	G21
2	2.8	0	BSC12	27	45.1	14.1	E21
3	11.6	0	BSC11	28	45.1	24.3	N2
4	14.4	0	BSC11	29	50.9	16.6	E31
5	13.3	6.5	BST1	30	53.7	16.6	G31
6	13.3	9.3	BST1	31	51.4	24.7	N3
7	28.6	5.8	BST2	32	59.5	21.7	C32
8	31.4	5.8	BST2	33	0	36.5	DC-1
9	33	0	BSC21	34	3.1	36.5	DC-1
10	35.8	0	BSC21	35	6.7	36.5	E12
11	44.2	0	BSC22	36	9.6	36.5	G12
12	45.1	3	BSC22	37	19.8	33.4	DC+1
13	51.3	0	BSC32	38	19.8	36.5	DC+1
14	54.1	0	BSC32	39	25.4	33.4	DC+2
15	63.6	0	BSC31	40	25.4	36.5	DC+2
16	66.4	0	BSC31	41	35.6	36.5	G22
17	64.1	7.7	BST3	42	38.5	36.5	E22
18	66.9	7.7	BST3	43	42.1	36.5	DC-2
19	0	16.4	E11	44	45.1	36.5	DC-2
20	2.8	16.4	G11	45	50.7	36.5	DC-3
21	0	24.7	N1	46	53.8	36.5	DC-3
22	9.1	21.7	C12	47	57.4	36.5	E32
23	25.4	17.7	TH2	48	60.3	36.5	G32
24	25.4	20.6	TH1	49	70.5	33.4	DC+3
25	37.4	21.5	C22	50	70.5	36.5	DC+3

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PIM56, 93x47 (SOLDER PIN)
CASE 180BK
ISSUE O

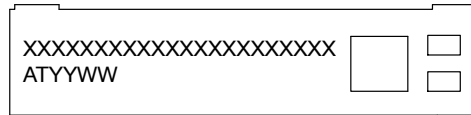
DATE 19 MAY 2022



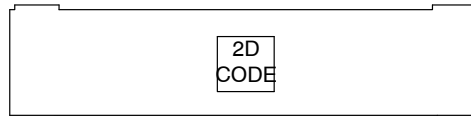
RECOMMENDED MOUNTING PATTERN

* For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

GENERIC MARKING DIAGRAM*



FRONTSIDE MARKING



BACKSIDE MARKING

XXXXX = Specific Device Code
 AT = Assembly & Test Site Code
 YYWW = Year and Work Week Code

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "•", may or may not be present. Some products may not follow the Generic Marking.

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